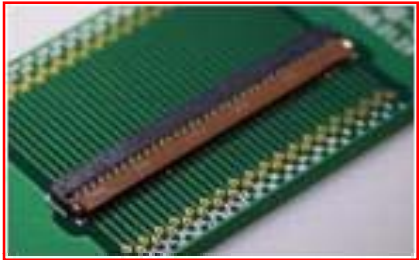

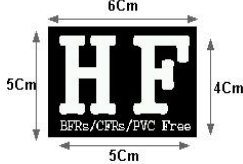




PRODUCT APPROVAL

Part Name	CONNECTOR	Product image
Title	PF030-O**B-C10-H	
Product Name	H=1.0mm FPC 0.3PITCH 'HF' TYPE CONNECTOR	
Revision	VER.5 08/10/2011	
A manufacturing company	Uju Electronics co.,Ltd.	

LEAD FREE	Halogen-Free
	

Office (KOREA) Manufacture ①	Drafting	ISS.	APP.
Uju Electronics co.,Ltd. 195-14. SACHANG-RI. YANGGAM-MYUN. HWASUNG-CITY. KYUNGGI-DO. KOREA. 445-932. Tel - 82 · 31· 371 - 3700 Fax - 82 · 31· 371 - 3800 www.uju.com	SIGN		
Manufacture ②		C.S.YOON	J.K.KIM
QINGDAO UJ ELECTRONICS CO.,LTD. Chengyangqu Chengqugongyeyuan Qingdaoshi, Shandongsheng, China. PC 266109 Tel : 86-532-8908-3700 Fax : 86-532-8908-3800 www.uju.com	DATE	08/10/2011	08/10/2011

【 CONTENTS 】

1. Contents	1
2. History	2
3. Title	
PF030-O**B-C10-H	3
4. Scope	3
5. Product description	3
6. Related standard	3
7. Ratings	3
8. Performance	
8.1 Appearance	4
8.2 Mechanical Performance	4
8.3 Electrical Performance	5
8.4 Environmental Performance	5~6
9. Precautions & Product store condition & packing specification	
9.1 Precautions for use	7
9.2 Product store condition	7
9.3 Packing condition	7
9.4 Quantity	7
9.5 Packing Method	7
9.6 Marking list	7
10. Precautions & Operation , Recommended FPC Construction	8~12
11. The notice of mounting process for SMT connector. (For all SMT connector)	13~14
Attach	
12. Product drawing	
PF030-O**B-C10-H	15
13. Packing drawing	
PF030-O**B-C10-H	16~17
14. Reliability Test Result	18~

REV

TITLE

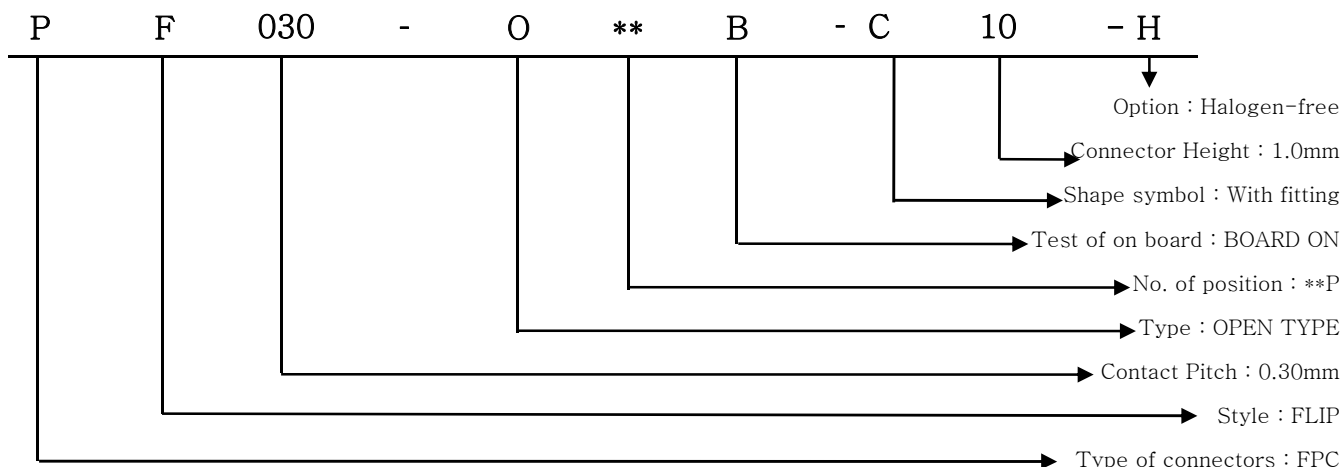
SHEET

E

PF030-O**B-C10-H

1 OF 14

3. Title



4. Scope

This specifies 0.3mm PITCH FPC (H=1.0) connector. The connector shall meet the performances specified here under condition with the connector and fpcb mates.

5. Product description

5.1 The PF030-O**B-C10-H consists of two plastic bases , ** contact terminals and two fitting nails.

5.2 Materials, Plating and marking.

PART	MATERIAL	FINISH / PLATING	VENDOR
BASE INSULATOR	LCP S475	BLACK COLOR	Polyplastics
ACTUATOR	PA46 HF4540	BROWN COLOR	DSM
CONTACT TERMINAL 'A'	PHOSPHOR BRONZE C5210-H t0.120mm	Nickel Barrier CONTACT : Au 0.1 μ m Min over Ni 1.0 μ m Min LEAD : Au flash over Nickel	Poong san / NIPPON
CONTACT TERMINAL 'B'	PHOSPHOR BRONZE C5210-H t0.120mm	Nickel Barrier CONTACT : Au 0.1 μ m Min over Ni 1.0 μ m Min LEAD : Au flash over Nickel	Poong san / NIPPON
FITTING NAIL	PHOSPHOR BRONZE C5210-H t0.100mm	Sn 1.0 μ m Min or Sn-Cu 1.0 μ m Min	Poong san

6. Related standard

MIL-STD-202 : Test method for Electronic and Electrical Component Parts.

7. Ratings

ITEM	STANDARD DATA
Current Rating	0.2A DC
Voltage rating	30V AC
Temperature in operation	-55℃ to +85 ℃
Temperature in preservation	
Applicable fpcb	Thickness : 0.2 \pm 0.03mm

REV	TITLE	SHEET
E	PF030-O**B-C10-H	3 OF 14

8. Performance

8.1 Appearance

ITEM	TEST METHOD	SPECIFICATION
Appearance	Visual Inspection	No rust, contamination, damage nor deformation effecting on function.
Appearance Dimension	–	Refer to drawings.

8.2 Mechanical Performance

ITEM	TEST METHOD	SPECIFICATION
PIN Retention	Measured withdrawal force that resin grips and supports Pin. (Velocity of withdrawal : 25±3mm/Min)	0.05 Kgf Min.
Actuator Open Force	Actuator open test shall be done with film inserted.	0.003kgf × N Min. N=pins
Withdrawal Force	A connector shall be soldered on a board. An applicable FPC(FFC) shall be pulled from a connector at a speed of 25mm/min and measured extraction force.	1) FPC horizontality direction 0.02kgf × N Min. N=pins 2) FPC verticality direction 0.016kgf × N Min. N=pins
Durability	Connectors shall be mated and unmated at a speed of 25mm per minute. without current applied. Number of mating and unmating / 20times.	Contact resistance : 100mΩ Max
Vibration	Current of 0.1A shall be applied during the testing The vibration shall be along each axis for the period of two hours with the maximum amplitude of 1.52mm and frequency of 10 to 55 to 10Hz according to MIL-STD-202 method 201.	1) Contact resistance : 100mΩ Max 2) Appearance : No damage, loose part no crack.

REV

TITLE

SHEET

E

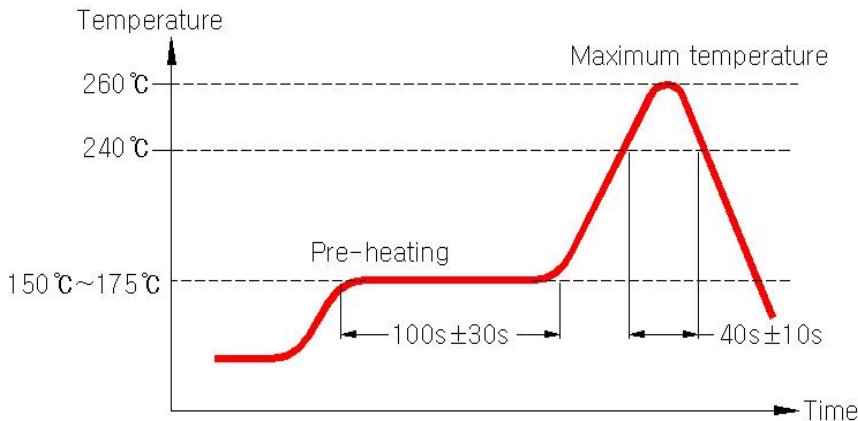
PF030-O**B-C10-H

4 OF 14

8.3 Electrical Performance

ITEM	TEST METHOD	SPECIFICATION
Insulation Resistance	Measured between adjacent contacts. Test voltage : DC 500V 1min±5sec (Based upon MIL-STD-202 Method 302 Condition B)	50MΩ Min
Dielectric withstanding voltage	Measured between adjacent contacts. Test voltage : AC 200V Electrification time : 1min/5sec (Based upon MIL-STD-202 Method 301)	No flash over and no physical damage shall be observed.
Contact Resistance	Measured the resistance of mated connector terminal and film 20mV, 1mA	100mΩ Max

8.4 Environmental Performance

ITEM	TEST METHOD	SPECIFICATION
Solderheat Resistance	Reflow condition. (Refer to Reflow)  <p>The graph shows Temperature (°C) on the Y-axis and Time on the X-axis. The profile starts at a baseline, rises to a pre-heating plateau at 150°C~175°C for 100s±30s, then rises to a maximum temperature peak at 260°C, and finally cools down for 40s±10s. Dashed horizontal lines indicate the 240°C and 260°C levels.</p>	No deformations and no damage should be observed.
Solderability	Immersion in Flux consisting of rosin 10% and methanol 90% for a period of 5 to 10 seconds dip in molten solder consisting of Sn-Ag-Cu at 260°C plus or minus 5 degrees for 3 plus or minus 0.5 seconds.	More than 90% of area dipped in molten solder should be coated by solder.
Salt spray	Measure after exposure to salt solution spray of 5±1% density at a temperature of 35°C±2°C for 48hr±4hr. After test wash and leave to dry.	1) Contact resistance : 100mΩ Max 2) Appearance : No damage, loose part no crack.

REV

TITLE

SHEET

E

PF030-O**B-C10-H

5 OF 14

8.4 Environmental Performance

ITEM	TEST METHOD	SPECIFICATION															
Humidity	Mated connectors shall be left in the chamber of 40±2℃ temperature and 90~95% humidity for 96hrs. After drying in ambient condition for 1 hours, measurement is done in accordance with MIL-STD-202, Method 103-B.	1) Contact resistance : 100mΩ Max 2) Appearance : No damage, loose part no crack. 3) Dielectric strength : No flash over and no physical damage shall be observed. 4) Insulation resistance : 50MΩ Min															
Resistance to high temperature	Leave in the chamber of Temperature 85℃ for 96hr. Check insulation resistance and dielectric strength.	1) Dielectric strength : No flash over and no physical damage shall be observed. 2) Contact resistance : 100mΩ Max 3) Appearance : No damage, loose part no crack.															
Altitude low temperature	Leave in the chamber of Temperature -40℃ for 96hr. Check insulation resistance and dielectric strength.	1) Dielectric strength : No flash over and no physical damage shall be observed. 2) Contact resistance : 100mΩ Max 3) Appearance : No damage, loose part no crack.															
Thermal shock	Mated connector shall be exposed five cycles as table #1 The testing shall be in accordance with MIL-STD-202, Method 107-A Table #1. <table><tr><td>STEP</td><td>1</td><td>2</td><td>3</td><td>4</td></tr><tr><td>TEM' (℃)</td><td>-55±3</td><td>25+10,-0</td><td>85±2</td><td>25+10,-5</td></tr><tr><td>Exposed time (MIN)</td><td>30</td><td>5</td><td>30</td><td>5</td></tr></table>	STEP	1	2	3	4	TEM' (℃)	-55±3	25+10,-0	85±2	25+10,-5	Exposed time (MIN)	30	5	30	5	1) Dielectric strength : No flash over and no physical damage shall be observed. 2) Contact resistance : 100mΩ Max 3) Insulation resistance : 50MΩ Min
STEP	1	2	3	4													
TEM' (℃)	-55±3	25+10,-0	85±2	25+10,-5													
Exposed time (MIN)	30	5	30	5													

REV

TITLE

SHEET

E

PF030-O**B-C10-H

6 OF 14

9. Precautions & Product store condition & packing specification

9.1 Precautions for using.

- 1) Please do not apply excessive force or shock when using this product.
- 2) Please do not drop the product while moving.
- 3) Please do not heap up too many products in reel package condition.
- 4) The product movement must be done in normal package condition.

9.2 Product storage condition. (Manufacturer Storage Standard)

1) The serviceable duration for each conditions.

- MOLD : 1 year from it is made.
- PRESS : 1 year from it is made.
- Assembly : 1 year from it is made.
- Packing : 1 year from it is made.

2) Storage temperature : 15~35℃

Please avoid storing the product for a long time in the abnormal temperature.

3) Storage humidity : 65%RH

9.3 Packing condition

- 1) Inner packing : BOBBIN – Φ380
- 2) Outer packing : Paper Box – 405 × 395 × 340mm

9.4 Quantity

- 1) PF030-O**B-C10-H : 5,000ea / 1 Reel

9.5 Packing Method

See packing drawing.

9.6 Marking list

- 1) Manufacture's logo
- 2) Title & Part Number
- 3) Quantity
- 4) Date Code
- 5) Other agreed substances between manufacturer and customer.

REV

TITLE

SHEET

E

PF030-O**B-C10-H

7 OF 14

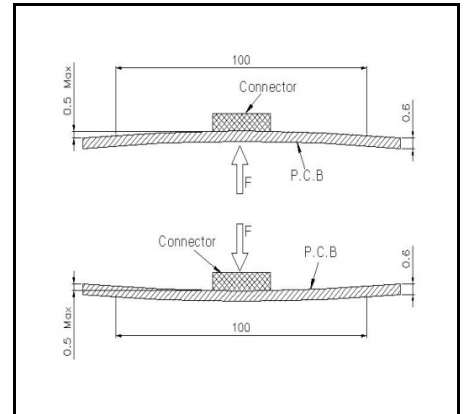
10. Precautions & Operation , Recommended FPC Construction

This Connector is very thin and small so needs careful treatment. Please confirm following recommendations.

10.1 Precautions for soldering connector on the PCB.

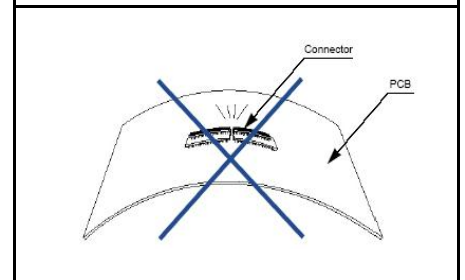
1) PC board deflection before mounting.

The connectors are straight within 0.08mm Max,
so please be careful not to use PCB with severe deflection.
Make sure the flatness of connector mounting area of PCB,
and verify whether it can accept the connector terminals without
any failure of the solder joint.



2) Handling the connectors before mounting on PCB.

Insertion of the FPC or operation of the actuator prior to mounting
on the PCB is NOT RECOMMENDED.



3) Handling the PCB.

Exercise caution when handing boards with the connectors installed.
Do not apply any forces affecting soldered joints.

4) Recommended specification for PCB deflection during the soldering.

Please do not use the PCB which deflects over 0.5mm per 100mm width during the soldering process.
The severe deflection of PCB can cause serious damages on the connector.

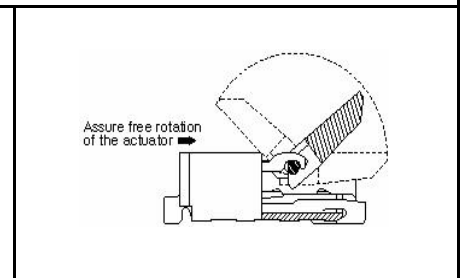
10.2 Actuator operation.

1) Please do not apply excessive forces when opening the actuator prior to FPC insertion.

Especially when you open it, please avoid touching the contacts with your finger or some tools.



2) When you open and close the actuator, please rotate it in the axis of rotation center which is specified on the figure of right.



REV

TITLE

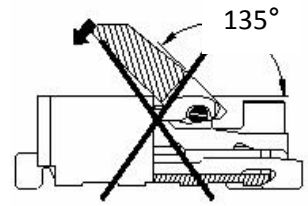
SHEET

E

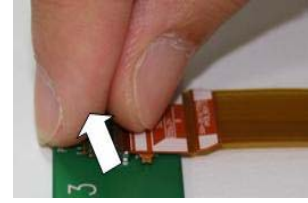
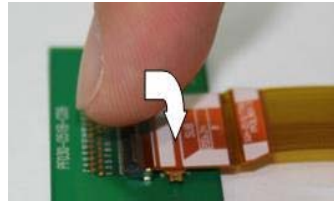
PF030-O**B-C10-H

8 OF 14

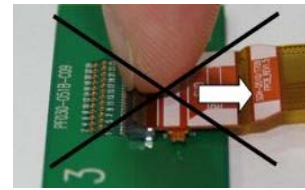
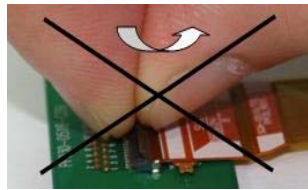
- 3) The actuator will rotate 135 degrees maximum.
Do not apply any excessive forces to rotate further.



- 4) When you operate the actuator, use the center portion of actuator.

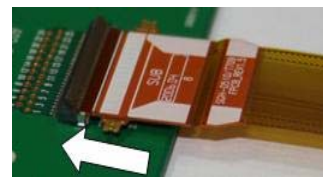
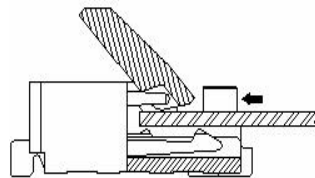


- 5) Please do not attempt to remove or re-position the actuator as shown below.



10.3 FPC insertion

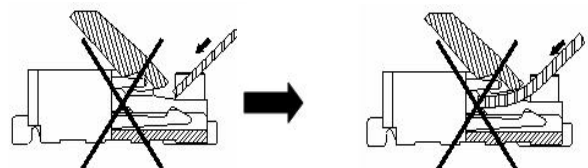
- 1) The FPC should be aligned parallel with the board surface and perpendicular with the connector first, (as shown), and then completely inserted.



To assure correct electrical and mechanical connection do not insert FPC with slanted direction.

The FPC must be fully inserted, and do not move it during the closing of the actuator.

- 2) Do not insert the FPC with steep angle from above.
As illustrated, insertion with steep angle can cause electrical discontinuity by deformation of contacts.



REV

TITLE

SHEET

E

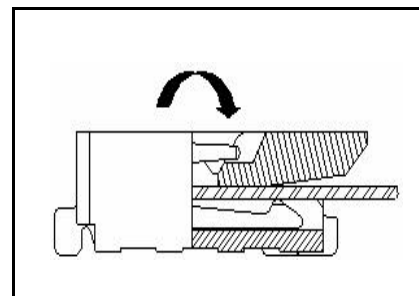
PF030-O**B-C10-H

9 OF 14

※To avert inclined insertion of the FPC , the sufficient consideration for securing the FPC insertion space is needed during the design of PCB.

※Please contact the FPC manufacturer for information about the bending specification.

- 3) The actuator should be fully closed (as illustrated)
and the FPC should be held firmly in the connector.

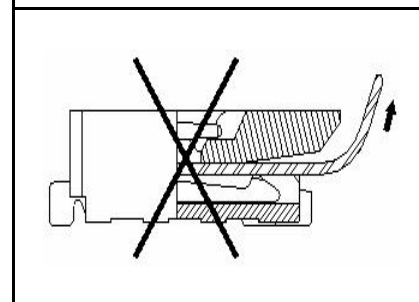


- 4) Verification of the full close of actuator.

Please verify whether the actuator is parallel to PCB plane.

Do not apply excessive force against the actuator when it is fully closed.

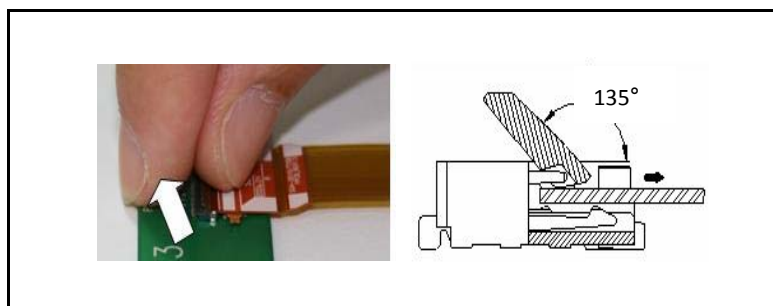
Max force applied to the fully closed actuator should not exceed 1N.



- 5) Precautions for the FPC which is fully inserted and fixed by actuator

Do not apply force in excess of 0.05N/pin max. in the upward direction as illustrated and do not bend the FPC too close to the actuator.

- 6) Rotate the actuator to the open position
maximum open angle of 135°.



10.4 Other Precautions

Hand Soldering Precautions.

When hand soldering.

Do not perform reflow or hand soldering with the FPC inserted in the connector leads.

Do not apply excessive heat or touch the soldering iron anywhere other than the connector leads.

Do not apply excessive amount of solder or flux compounds.

Operation of the actuator and contacts may be affected by excessive amounts of solder or flux compounds.

REV

TITLE

SHEET

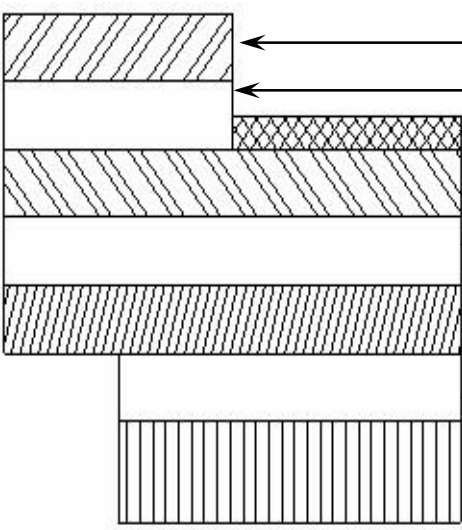
E

PF030-O**B-C10-H

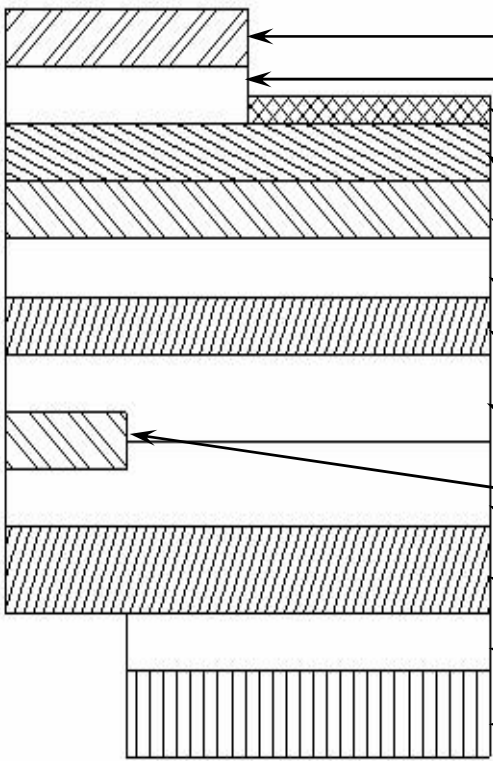
10 OF 14

【Recommended FPC Construction】

1. Using Single-sided FPC

		Material Name	Material	Thickness(μm)
		Covering film layer	Polyamide 1mil thick	25
		Cover adhesive		25
		Surface treatment	Tin-lead plated	5
			Ni under plated 1to5μm	(3)
			Gold plated 0.2μm	
		Copper foil	Cu 1/2oz	35
		Base adhesive	Thermosetting adhesive	25
		Base film	Polyamide 1mil thick	25
		Reinforcement material adhesive	Thermosetting adhesive	40
		Stiffener	Polyamide 3mil thick	75
Total				205 (203)

2. Using Double-sided FPC

		Material Name	Material	Thickness(μm)
		Covering film layer	Polyamide 1mil thick	25
		Cover adhesive		25
		Surface treatment	Tin-lead plated or	5
			Ni under plated 1to5μm	(3)
			Gold plated 0.2μm	
		Through-hole copper	Cu	15
		Copper foil	Cu 1/2oz	18
		Base adhesive	Thermosetting adhesive	18
		Base film	Polyamide 1mil thick	25
		Base adhesive	Thermosetting adhesive	18
		Copper foil	Cu 1/2oz	18
		Cover adhesive	Thermosetting adhesive	25
		Covering film layer	Polyamide 1mil thick	25
		Reinforcement material adhesive	Thermosetting adhesive	25
		Stiffener	Polyamide 1mil thick	25
Total				199 (197)

3. NOTE

- 1) This specification is a recommendation for the FPC 0.3PITCH Series connectors using FPC t:0.20±0.03mm thick.
- 2) For details about the construction, please contact the FPC manufacturers.

REV

TITLE

SHEET

E

PF030-O**B-C10-H

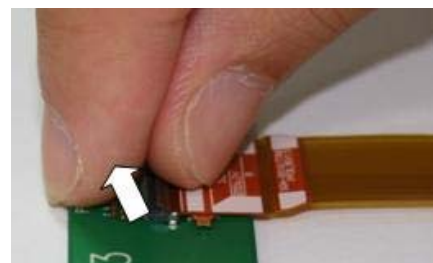
11 OF 14

【Connector operation and precautions】

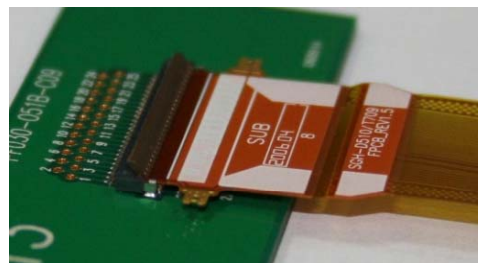
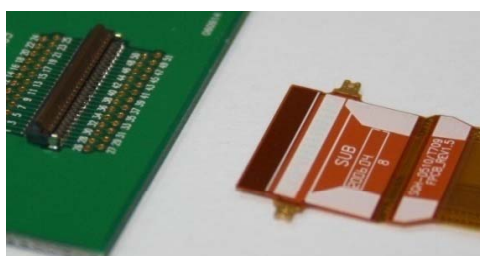
Operation

1. FPC insertion procedure. Connector installed on the board.

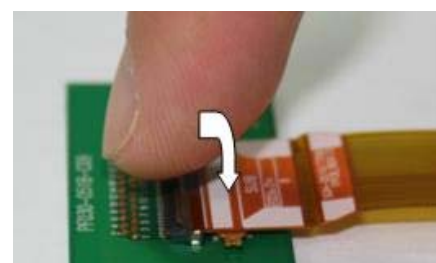
1) Lift up the actuator. Use thumb or index finger.



2) Fully insert FPC in the connector parallel to mounting surface, with the exposed conductive traces facing down.

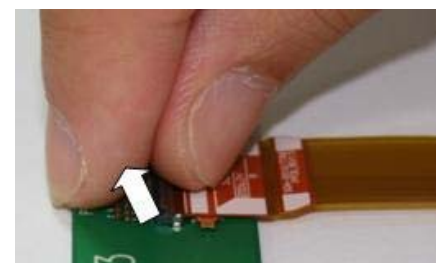


3) Rotate down the actuator until firmly closed. It is critical that the inserted FPC is not moved and remains fully inserted.



2. FPC removal

1) Lift up the actuator. Carefully withdraw the FPC.



REV

TITLE

SHEET

E

PF030-O**B-C10-H

12 OF 14

11. The notice of mounting process for SMT connector. (For all SMT connector)

Introduction

This guideline is provided for correct application of SMT connectors under the automatic mounting machine.

User always necessary to refer to the specification that provided in the drawing of each connector and pay attention to following notices.

Since in the actual mounting process, the conditions might be changed according to equipment, machines, ect.

must do always check the mounting conditions before production is to start.

11.1 Designing of printed circuit board :

For reference, each connector drawing has provided with the recommended PCB dimensions.

11.2 Solder paste printing :

1) Read through the document Uju profile (Uju Ltd. Recommended Temperature Profiles) that provided guideline about solder pastes and temperature profile. However soldering conditions might be changed on each equipment, machine, ect. So do always check soldering condition before starting production.

2) When applying solder paste, recommend to apply the solder paste by the screen printing method.

Regarding the metal mask dimension. Do always refer to the dimensions that specified in each connector drawing.

11.3 Selecting the Automatic Mounting Machine and Mounting Connector.

1) When selecting the mounting machine, always consider its positioning accuracy, connector shape, and other factors that might cause misplacement.

2) Some connectors may not be able to keep sitting on the PCB or it might fall down during soldering process.

To solve this problem. Recommended to use some kinds of supporting jig.

3) When using the vacuum picking up style mounting machine, Do select the suitable shape of nozzle for picking to the certain area of connector.

Refer to vacuum picking area that specified in connector drawing.

4) When you are using the mechanical picking style mounting machine, control chucking force to prevent the deformation of connector housing and metal parts. Always check the chucking force when starting production.

5) To prevent the deformation of connector housing and metal parts during mounting connector on the PCB. do not apply any excessive force to the connector.

6) To prevent mis-soldering, once put the connector on the PCB, NOTICES that all contact terminals touch the solder paste thoroughly.

7) When mounting connector on PCB, recommend to use mounting machine that capable to place on the correct positioning . DO NOT use the dowel pin,. (for reverse mounting prevention) to positioning since it might cause mis-alignment.

8) Normally connectors provided under the standard package , it may not be suitable for positioning the connector picked up by mounting machine. Recommend to check picking up condition before starting production.

11.4 Reflow Soldering

1) To select the suitable temperature profile, Do always refer to the profiles that recommended in document Uju profile since it might be changed by machine, solder paste, restriction from other components mounted on the same PCB with connectors, ect.

2) When measuring temperature profiles, put the sensor on the specified positions (refer to document Uju profile) In particular, for large-size connector, be careful about the problem of mis-soldering that may be cause from temperature difference in the connector body.

REV

TITLE

SHEET

E

PF030-O**B-C10-H

13 OF 14

- 3) In case of both sides of PCB mounting, if the connector is mounted on the bottom side of PCB, do apply the adhesive/glue to the connectors to prevent falling off during reflow process.
Also make sure that contact terminals shall never uplift from the PCB.
- 4) To prevent electrical failure when mating the connectors, during solder process always avoid the flux that may raise up or spread to the contact mating area particularly in case of mounting the connector at the PCB's edge or near the through-holes.
- 5) Do not use the warped PCB. To keep PCB flatness during reflow process, use jig or other equipments to prevent mis-soldering of contact terminals.

11.5 Soldering Rework

- 1) To prevent connector housing damage from excessive temperature, Do always control the soldering iron temperature under 360℃, and finish the touch up work within 3 seconds.
- 2) Always clean the tip of soldering iron thoroughly.
- 3) Finish a touch up work at once. Never leave it over time.
- 4) Pay attention to any excessive force that might cause contact-terminals deformation and/or connector malfunction.
- 5) Electrical failure might cause from soldering flux rising up or spreading that contaminating the contact area.
To avoid from this phenomenon, either using some protector like cover and never apply overwhelming flux around contact terminal and PCB.

11.6 Storage Conditions for Connectors.

- 1) To prevent blistering on connector housing during reflow process.
Do not keep or storage the connectors in high moisture place. For long-term storage. Do always keep the connectors where temperature and humidity are properly controlled.
Normally , for good solderability, connector's shelf life recommended is within 6 months after manufacturing date. If keep longer than 6 months, Do always check its solderability before starting production.
- 2) To prevent the deformation of contacts or connector housing , do not apply any excessive force during the storage or transportation.
- 3) To prevent electrical contacting failure, do not store connector in a dusty area.
- 4) Each manufacturing lot, connector color might be seen a little differently, but it does not affect its functionality.

11.7 Others.

- 1) Dropping connector to the floor from height position or applying excessive force on contact terminals, may cause troubles such as mis-soldering, contact deformation, or broken housing.
- 2) To prevent contacts deformation or other affect, Do not mate and un-mate the connectors before soldering them on the PCB. If necessary, do it with care.
- 3) In case of the PCB pairs (with connectors mounted) that has notch lines to break off, Do not apply any excessive force to soldered part of connector to prevent solder peeling problem.
- 4) In case of the PCB is to be coated with chemical materials to prevent from a degradation of insulation after mounted connectors, do not stain the connector with any chemical materials.
- 5) During transferring the connector or PCB (with connector mounted) , to prevent from contact or housing deformation, do not apply any excessive force on the connector.
- 6) This document is only the guidelines for correct mounting SMT connectors. Therefore, it does not intent to guaranteed the soldering quality of this product. For the purpose of product modification, the above contents can be changed without prior notices.

REV

TITLE

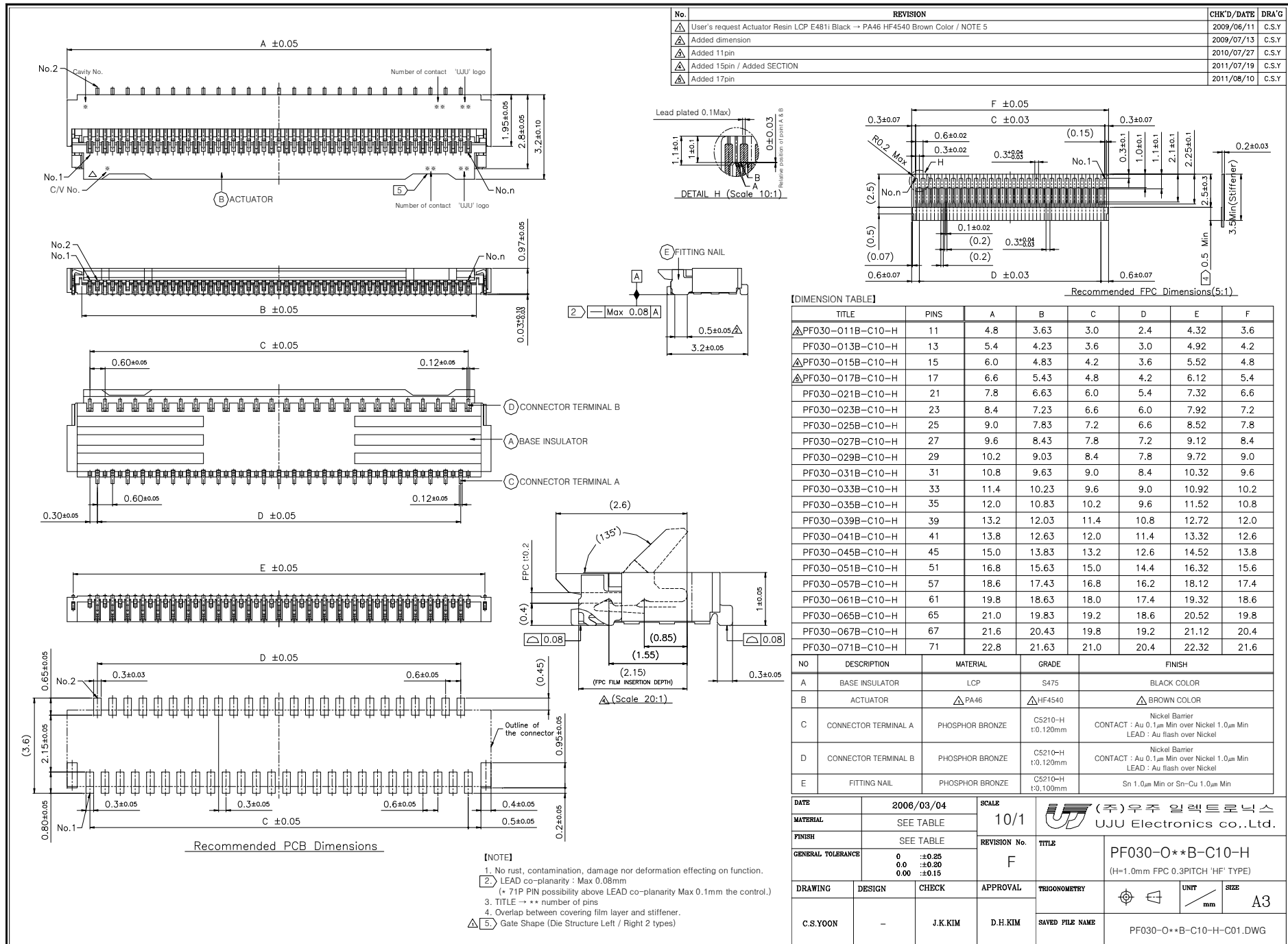
SHEET

E

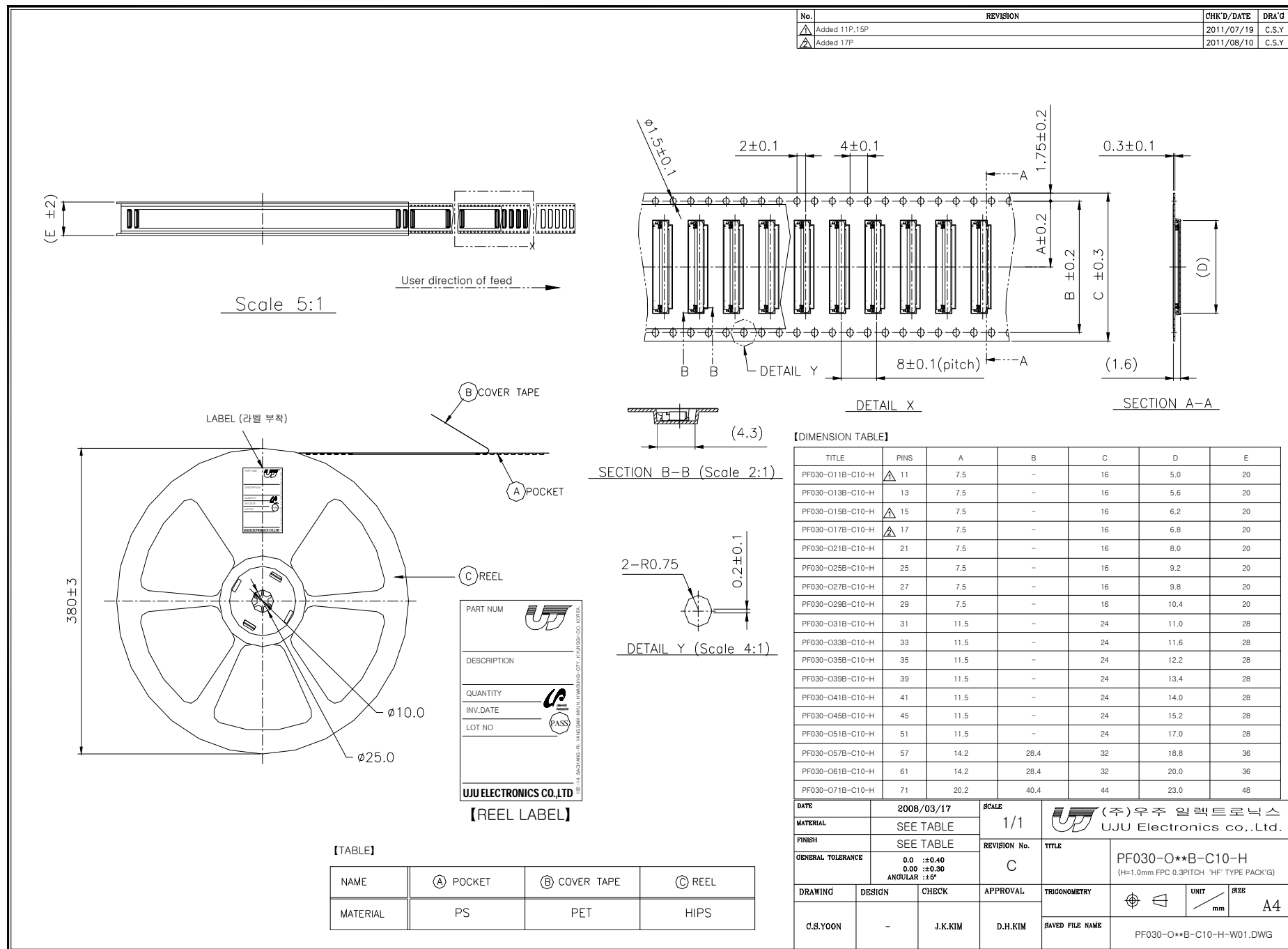
PF030-O**B-C10-H

14 OF 14

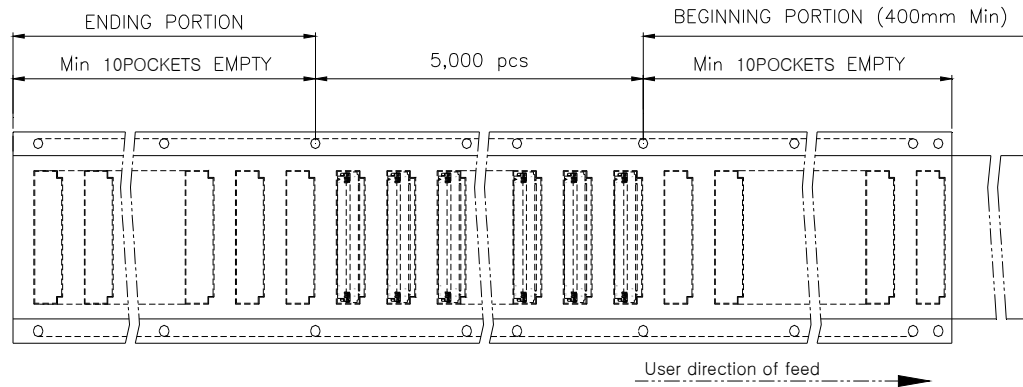
12. PRODUCT DRAWING



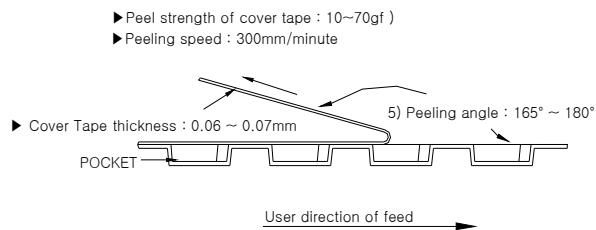
13. PACKING DRAWING



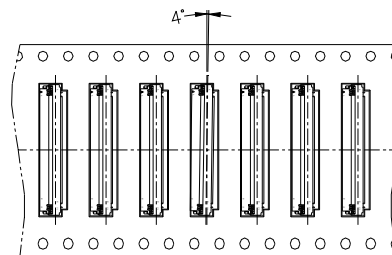
【REFERENCE 1】



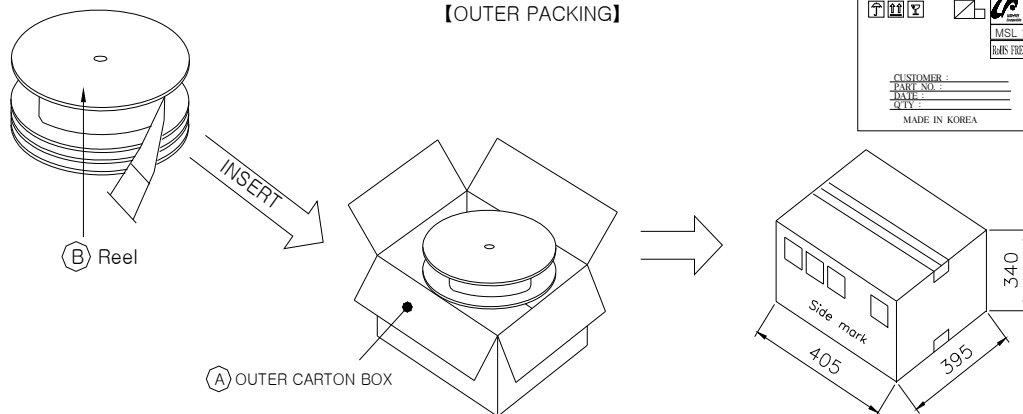
【REFERENCE 1】



【REFERENCE 2】



【OUTER PACKING】



No.	REVISION	CHK'D/DATE	DRA'G
△	Added 11P,15P	2011/07/19	C.S.Y
△	Added 17P	2011/08/10	C.S.Y

◆ EMBOSS TAPE SPECIFICATION

【REFERENCE 1】

- Quantity : 5,000pcs / 1 Reel
- Beginning portion - Empty 10pockets min , Ending portion - Empty 10pockets min.
- Peel strength of cover tape : 10~70gf
- Peeling speed : 300mm/minute
- Peeling angle : 165° ~ 180°
- Cover Tape thickness : 0.06 ~ 0.07mm

【REFERENCE 2】

- Product angle in pocket would be tilt : 4.0°

<< NOTE >>

- Reel 5,000pcs packing.
- Outer carton box packing.
△ 1) 11p ~ 29p → 5,000pcs × 14reel = 70,000pcs
2) 31p ~ 51p → 5,000pcs × 10reel = 50,000pcs
3) 57p ~ 61p → 5,000pcs × 8reel = 40,000pcs
4) 65p ~ 71p → 5,000pcs × 6reel = 30,000pcs
- Horizontal packing.
- Outer carton box size : 405(width) × 395(length) × 340(height)
- Reel - Adhesive of label.
- Outer box - Lead free mark & box label.

CUSTOMER		【TABLE】	
CUSTOMER CODE		NO.	NAME
EA		A	OUTER CARTON BOX
년 . 월 . 일		B	REEL
			MATERIAL (재질)
			Corrugated cardboard (골판지)
			HIPS

DATE	2008/03/17	SCALE	N/S	(주)우주 일렉트로닉스 UJU Electronics co.,Ltd.	
MATERIAL	SEE TABLE	REVISION No.	C	TITLE	PF030-O**B-C10-H
FINISH	-				(H=1.0mm FPC 0.3PITCH 'HF' TYPE PACK'G)
GENERAL TOLERANCE	X	APPROVAL		TRIGONOMETRY	
DRAWING	DESIGN	CHECK		UNIT	mm
C.S.YOON	-	J.K.KIM	D.H.KIM	SIZE	A4
				SAVED FILE NAME	PF030-O**B-C10-H-W02.DWG